

Title (en)

GALVANIC PLATING MODULE OF A HORIZONTAL GALVANIC PLATING LINE FOR GALVANIC METAL DEPOSITION ON A SUBSTRATE

Title (de)

GALVANISIERUNGSMODUL EINER HORIZONTAL EN GALVANISIERUNGSANLAGE ZUR GALVANISCHEN METALLABSCHIEDUNG AUF EINEM SUBSTRAT

Title (fr)

MODULE DE DÉPÔT GALVANIQUE D'UNE LIGNE DE DÉPÔT GALVANIQUE HORIZONTAL POUR UN DÉPÔT ÉLECTROLYTIQUE SUR UN SUBSTRAT

Publication

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Application

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Priority

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Abstract (en)

The present invention is related to galvanic plating module of a horizontal galvanic plating line for galvanic metal, preferably copper, deposition on a substrate; wherein said galvanic plating module comprises an inlet area, a plating device, and an outlet area, wherein the inlet area is arranged on one side of the plating device while the outlet area is arranged subsequently on the other side of the plating device in a transport direction of the substrate; wherein the plating device comprises an inlet side, an outlet side, an upper part and/or a lower part, and at least one first transport element for simultaneously transporting and electrically contacting the substrate during its transportation at a transport level in transport direction; and wherein the inlet area and/or the outlet area of the galvanic plating module comprises at least a second transport element for transporting the substrate during its transportation at a transport level in transport direction, wherein the galvanic plating module comprises further at least two substrate guiding elements being in conjunction with said plating device and said second transport element, wherein said substrate guiding elements are arranged between said plating device and said second transport element below and/or above the transport level of the substrate. Further, the present invention is generally directed to a kit for a galvanic plating module for galvanic metal, preferably copper, deposition on a substrate. The invention also relates to a method for adapting a galvanic plating module for galvanic metal, preferably copper, deposition on a substrate by making use of such a kit.

IPC 8 full level

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Citation (search report)

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